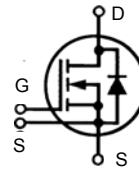


HiPerFET™ Power MOSFETs Single Die MOSFET

N-Channel Enhancement Mode
Avalanche Rated, High dv/dt, Low t_{rr}

IXFN 130N30

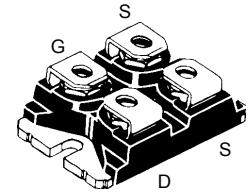


$V_{DSS} = 300$ V
 $I_{D25} = 130$ A
 $R_{DS(on)} = 22$ mΩ
 $t_{rr} \leq 250$ ns

miniBLOC, SOT-227 B (IXFN)



E153432



G = Gate D = Drain
S = Source

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	300	V
V_{DGR}	$T_J = 25^\circ\text{C}$ to 150°C ; $R_{GS} = 1$ MΩ	300	V
V_{GS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	$T_c = 25^\circ\text{C}$	130	A
$I_{L(\text{RMS})}$	Terminal (current limit)	100	A
I_{DM}	$T_c = 25^\circ\text{C}$, pulse width limited by T_{JM}	520	A
I_{AR}	$T_c = 25^\circ\text{C}$	100	A
E_{AR}	$T_c = 25^\circ\text{C}$	85	mJ
E_{AS}	$T_c = 25^\circ\text{C}$	4	J
dv/dt	$I_s \leq I_{DM}$, $di/dt \leq 100$ A/μs, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 2$ Ω	5	V/ns
P_D	$T_c = 25^\circ\text{C}$	700	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
V_{ISOL}	50/60 Hz, RMS $t = 1$ min $I_{ISOL} \leq 1$ mA $t = 1$ s	2500 3000	V~
M_d	Mounting torque Terminal connection torque	1.5/13 Nm/lb.in. 1.5/13 Nm/lb.in.	
Weight		30	g

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
V_{DSS}	$V_{GS} = 0$ V, $I_D = 3$ mA	300		V
$V_{GH(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 8$ mA	2		V
I_{GSS}	$V_{GS} = \pm 20$ V _{DC} , $V_{DS} = 0$		±200	nA
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0$ V	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	100 2	μA mA
$R_{DS(on)}$	$V_{GS} = 10$ V, $I_D = 0.5 \cdot I_{D25}$ Pulse test, $t \leq 300$ μs, duty cycle d ≤ 2 %		22	mΩ

Features

- International standard packages
- miniBLOC, with Aluminium nitride isolation
- Low $R_{DS(on)}$ HDMOST™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- Fast intrinsic Rectifier

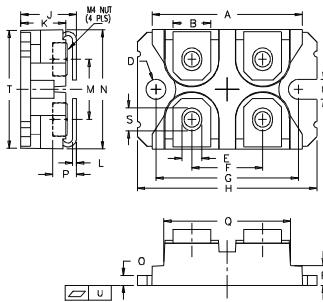
Applications

- DC-DC converters
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- Temperature and lighting controls

Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values			
		(T _J = 25°C, unless otherwise specified)	min.	typ.	max.
g_{fs}	V _{DS} = 10 V; I _D = 60A, pulse test	70	92	S	
C_{iss} C_{oss} C_{rss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz	14500		pF	
		2650		pF	
		610		pF	
t_{d(on)} t_r t_{d(off)} t_f	V _{GS} = 10 V, V _{DS} = 0.5 • V _{DSS} , I _D = 0.5 • I _{D25} R _G = 1 Ω (External),	45		ns	
		75		ns	
		130		ns	
		31		ns	
Q_{G(on)} Q_{GS} Q_{GD}	V _{GS} = 10 V, V _{DS} = 0.5 • V _{DSS} , I _D = 0.5 • I _{D25}	380		nC	
		95		nC	
		180		nC	
R_{thJC}			0.18	K/W	
R_{thCK}			0.05	K/W	

miniBLOC, SOT-227 B


M4 screws (4x) supplied

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	38.00	38.23	1.496	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.76	0.84	0.030	0.033
M	12.60	12.85	0.496	0.506
N	25.15	25.42	0.990	1.001
O	1.98	2.13	0.078	0.084
P	4.95	5.97	0.195	0.235
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.174
S	4.72	4.85	0.186	0.191
T	24.59	25.07	0.968	0.987
U	-0.05	0.1	-0.002	0.004

Source-Drain Diode
Characteristic Values
(T_J = 25°C, unless otherwise specified)

Symbol	Test Conditions	min.	typ.	max.
I_s	V _{GS} = 0 V		130	A
I_{SM}	Repetitive; pulse width limited by T _{JM}		520	A
V_{SD}	I _F = 100A, V _{GS} = 0 V, Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %		1.5	V
t_{rr}	I _F = 30A, -di/dt = 100 A/μs, V _R = 100 V	0.8	250	ns
Q_{RM}		8		μC
I_{RM}				A

IXYS reserves the right to change limits, test conditions, and dimensions.

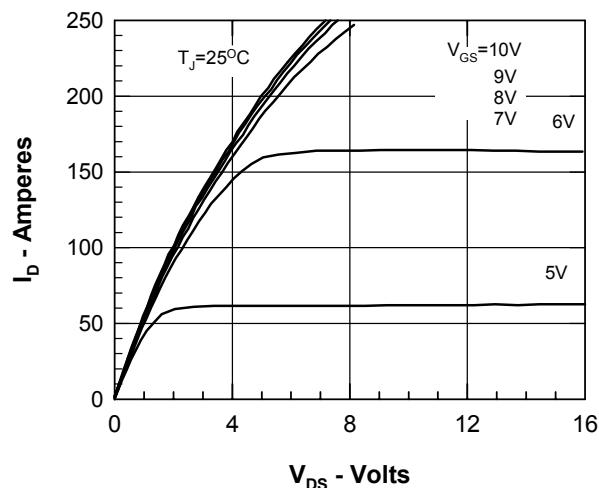


Figure 1. Output Characteristics at 25°C

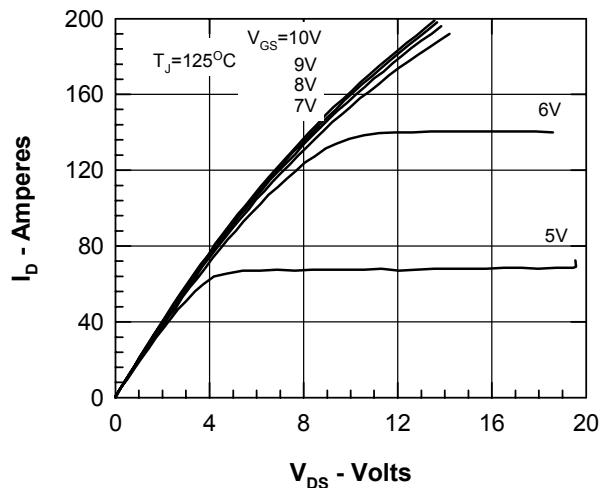


Figure 2. Output Characteristics at 125°C

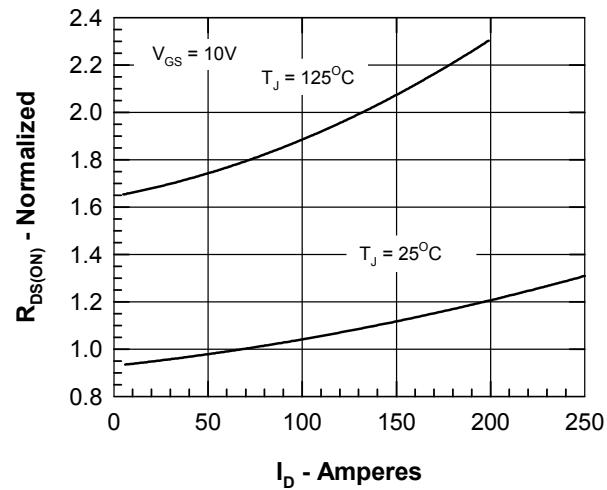


Figure 3. $R_{DS(on)}$ normalized to $0.5 I_{D25}$ value vs. I_D

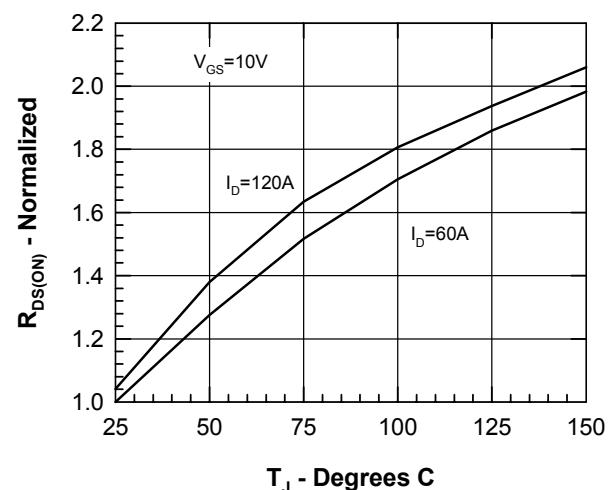


Figure 4. $R_{DS(on)}$ normalized to $0.5 I_{D25}$ value vs. T_J

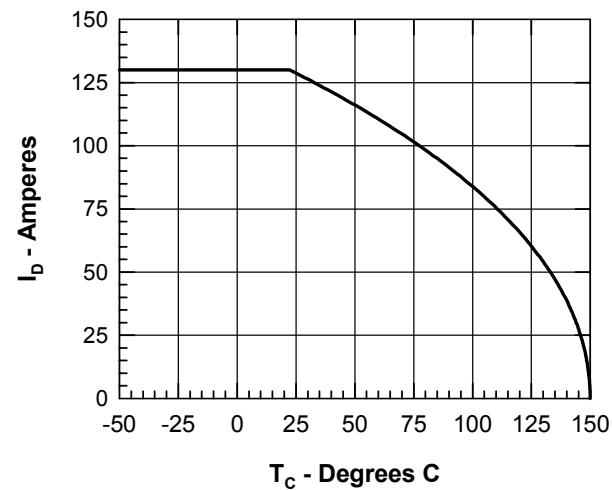


Figure 5. Drain Current vs. Case Temperature

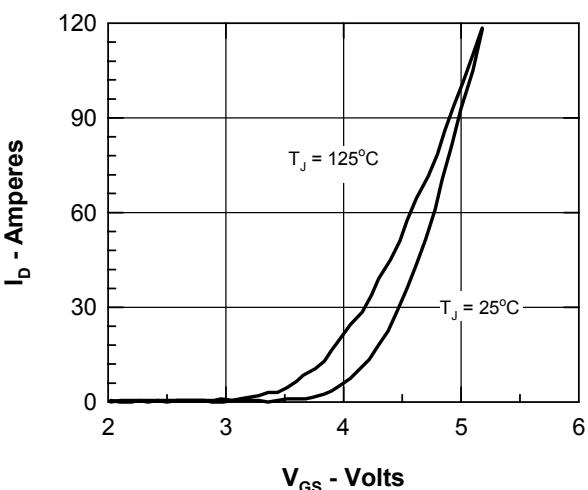


Figure 6. Admittance Curves

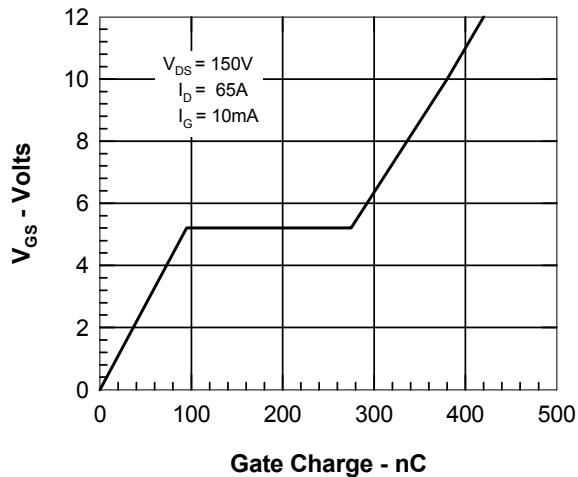


Figure 7. Gate Charge

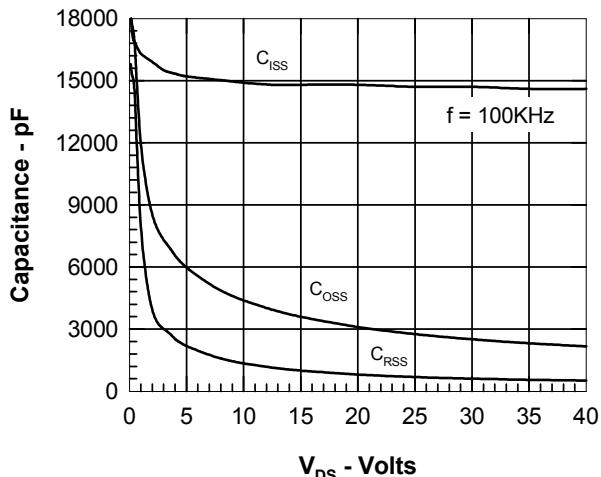


Figure 8. Capacitance Curves

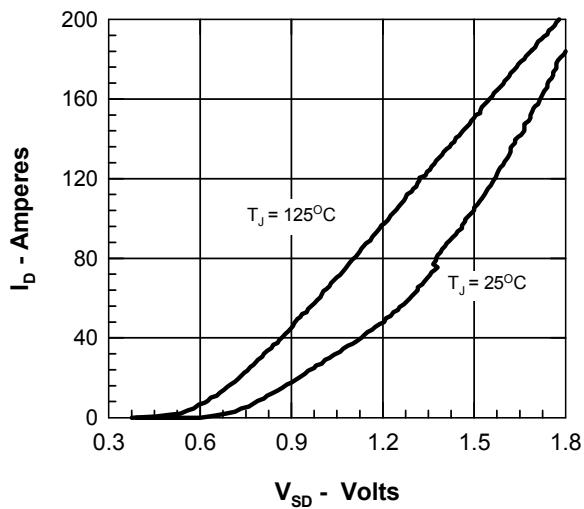


Figure 9. Forward Voltage Drop of the Intrinsic Diode

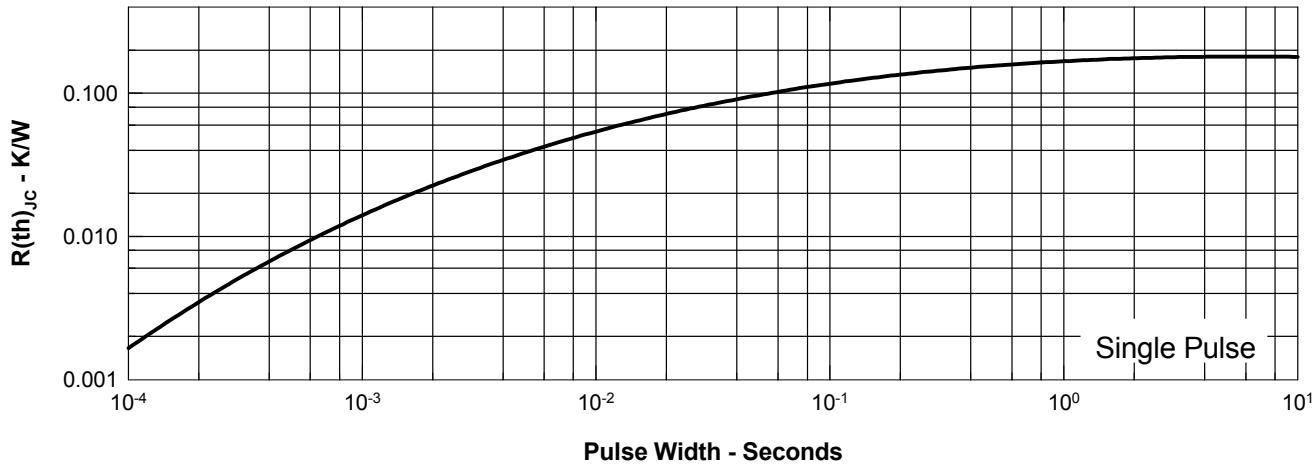


Figure 10. Transient Thermal Resistance

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592 4,850,072	4,881,106 4,931,844	5,017,508 5,034,796	5,049,961 5,063,307	5,187,117 5,237,481	5,486,715 5,381,025	6,306,728B1
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